



US00D873227S

(12) **United States Design Patent** (10) **Patent No.:** **US D873,227 S**
Yoneyama et al. (45) **Date of Patent:** **** Jan. 21, 2020**

(54) **SEMICONDUCTOR DEVICE**

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(**) Term: **15 Years**

(21) Appl. No.: **29/694,650**

(22) Filed: **Jun. 12, 2019**

Related U.S. Application Data

(62) Division of application No. 29/643,231, filed on Apr. 5, 2018.

(30) **Foreign Application Priority Data**

Oct. 23, 2017 (JP) 2017-023416
Oct. 23, 2017 (JP) 2017-023417

(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; 257/678, 684, 690, 691;
361/713, 728, 736, 760, 761, 772, 775,
361/783, 820; 174/250, 253; 438/15, 25,
438/26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;
H01L 2021/00; H01L 2021/02; H01L
2021/04; H01L 21/4814; H01L 21/4846;
H01L 21/4871; H01L 21/67144; H01L
23/12; H01L 23/13; H01L 23/14; H01L
23/147; H01L 2924/171; H01L
2924/1711; H01L 2924/1715; H01L

2924/17151; H01L 2924/181; H01L
2924/1811; H01L 2924/1815; H01L
2924/19042; H01L 2924/1905; H01L
2224/08054; H01L 23/58; H05B 41/14;
H02B 6/4201; G02B 6/4256; G02B
6/4257; G02B 6/4261; G02B 6/4262;
G02B 6/428; G02B 6/4281; H05K 1/14;
H05K 1/141; H05K 1/142; H05K 1/144;
H05K 1/18; H05K 1/181; H05K 1/182;
H05K 1/026

See application file for complete search history.

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PC

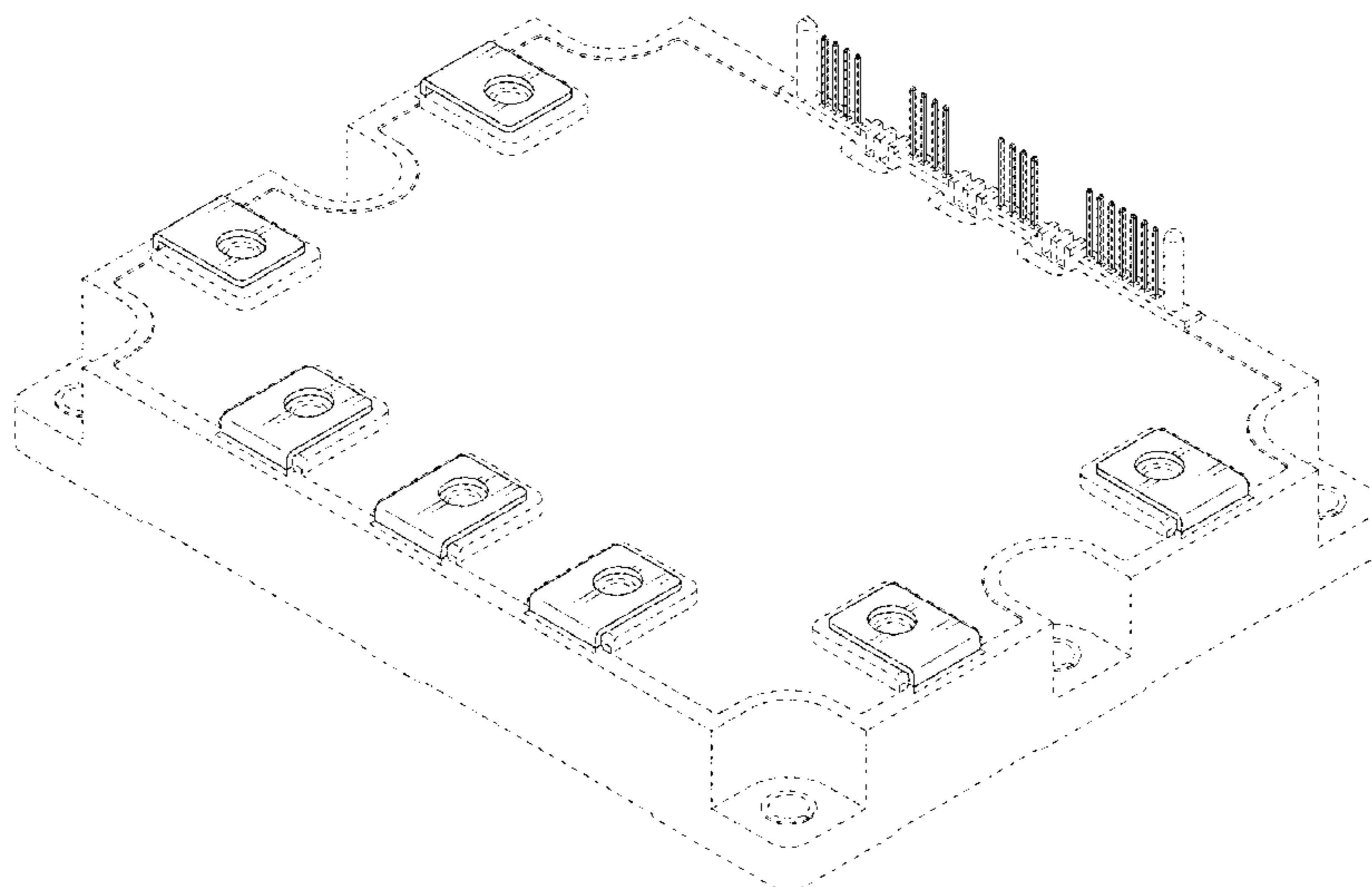
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a front, bottom and right side perspective view of a semiconductor device showing our new design;
FIG. 2 is a front view thereof;
FIG. 3 is a rear view thereof;
FIG. 4 is a top view thereof;
FIG. 5 is a bottom view thereof;
FIG. 6 is a left side view thereof; and,
FIG. 7 is a right side view thereof.
The broken lines illustrate portions of the semiconductor device that form no part of the claimed designs.

1 Claim, 5 Drawing Sheets



(56)

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Fig. 1

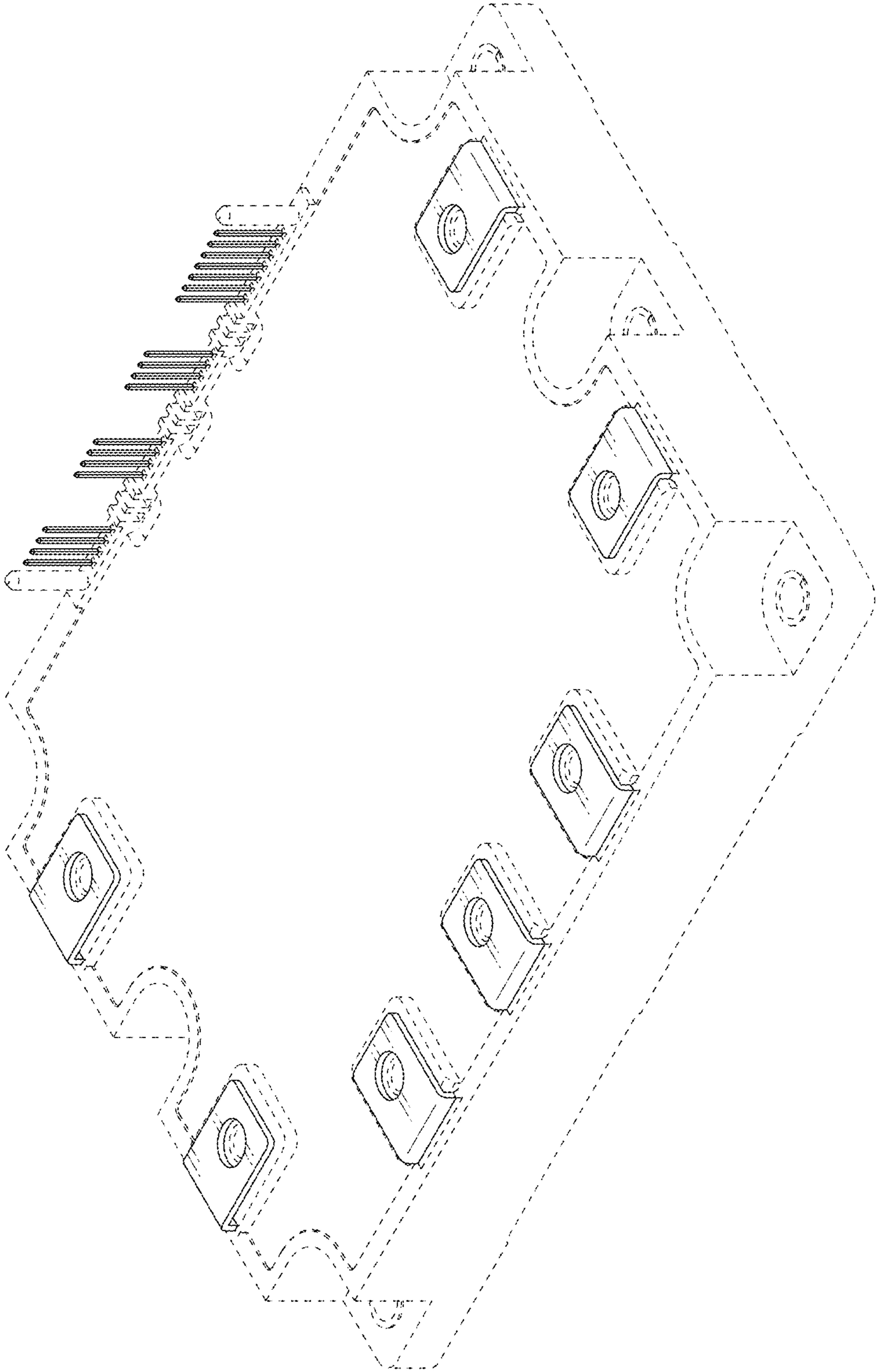


Fig. 2

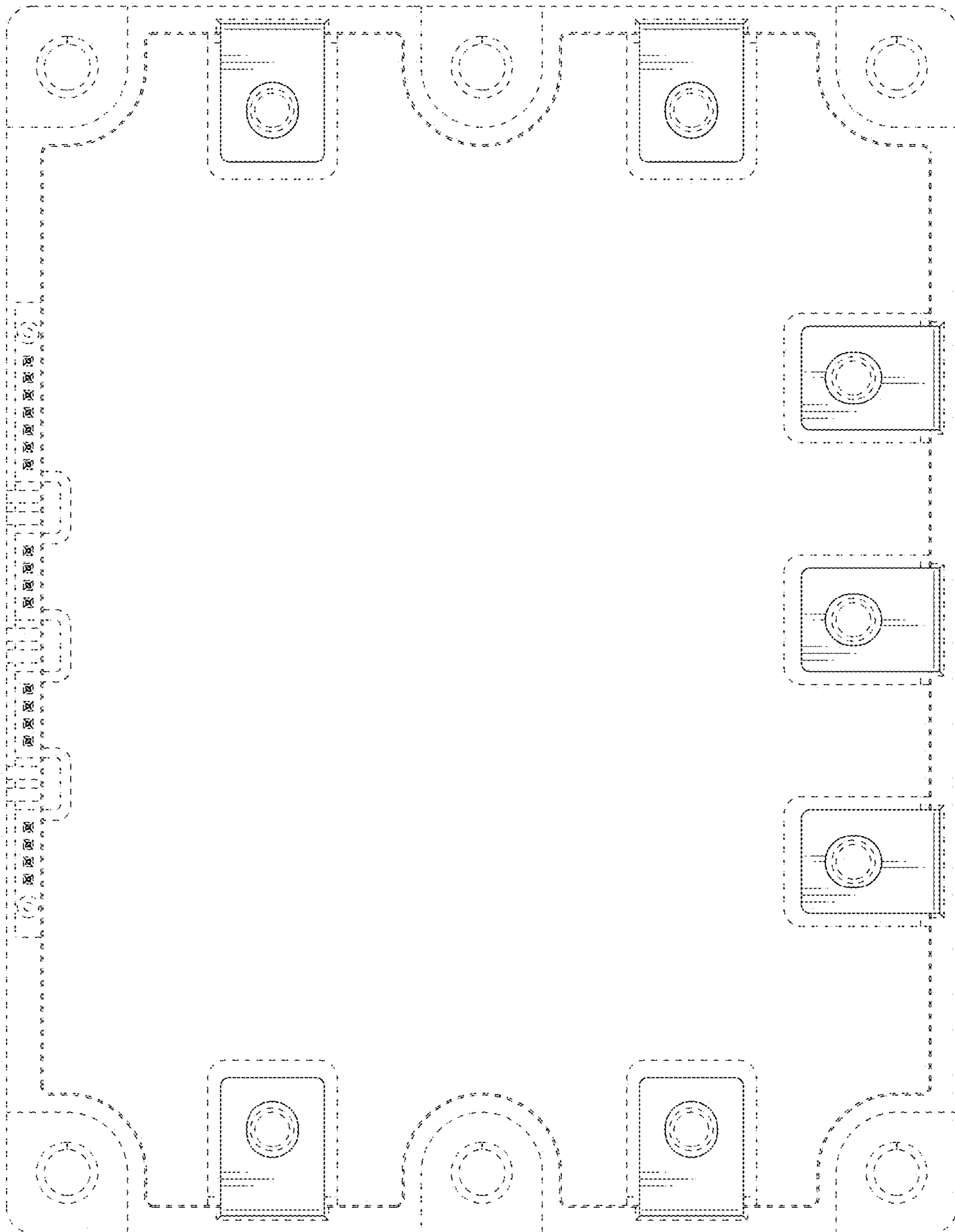


Fig. 3

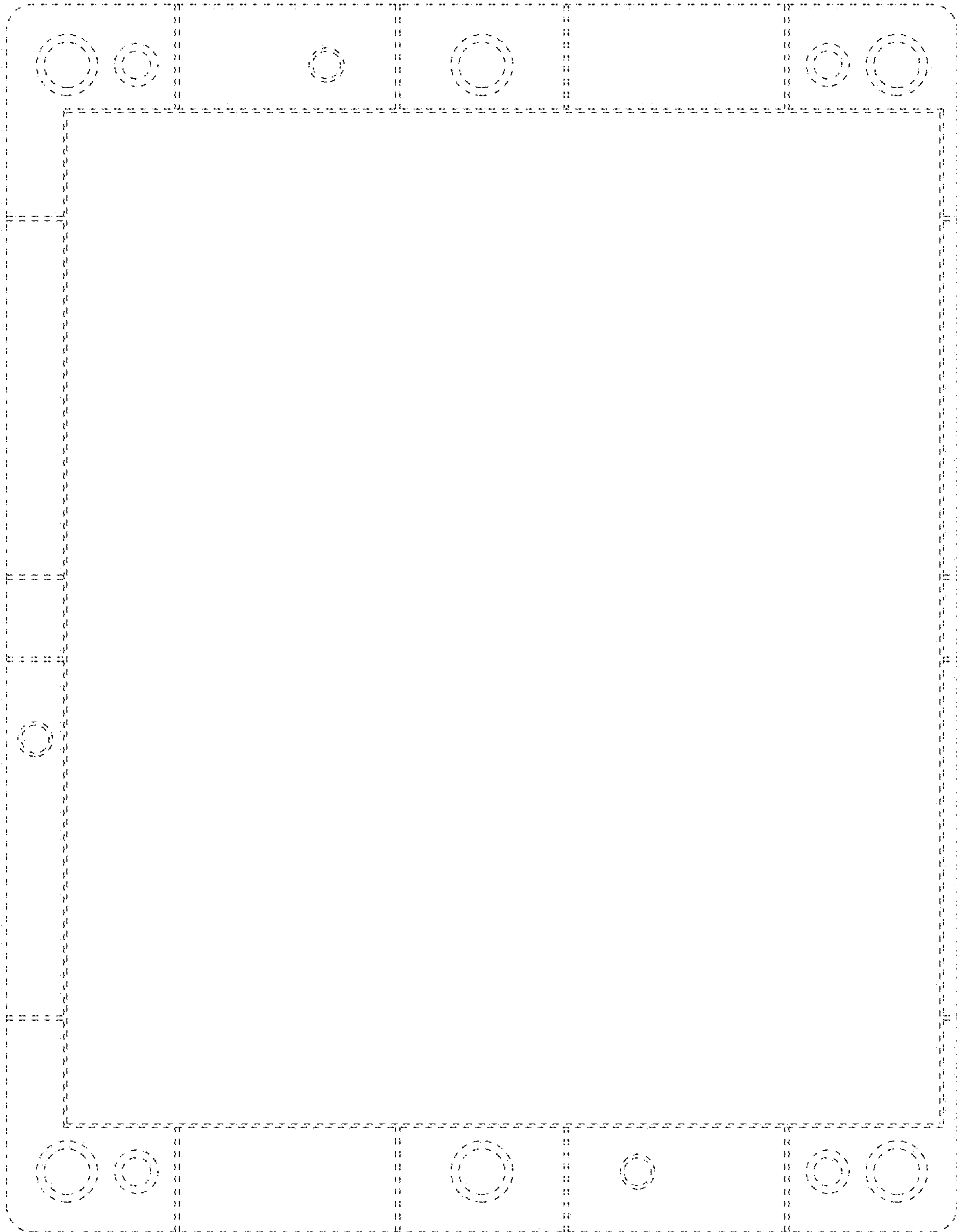


Fig. 4

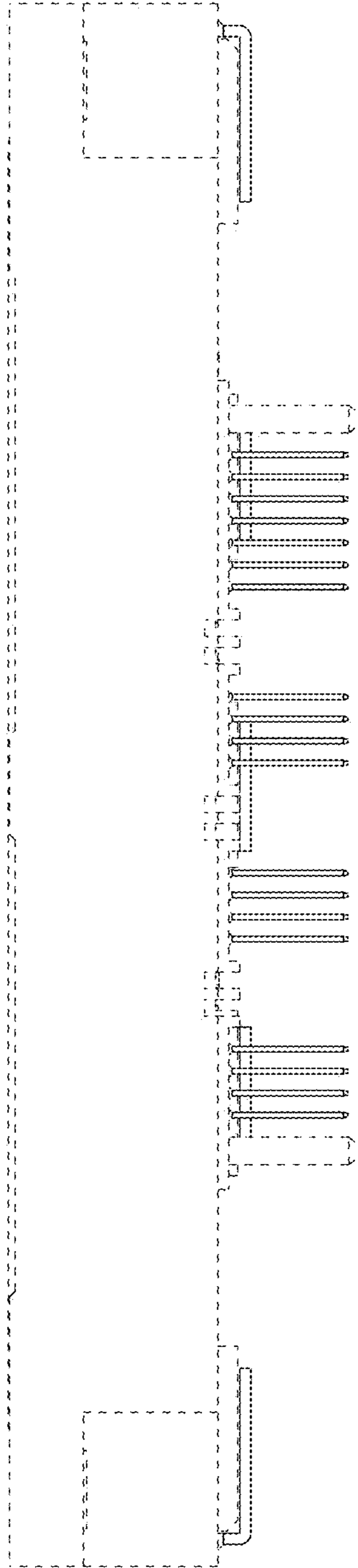


Fig. 5

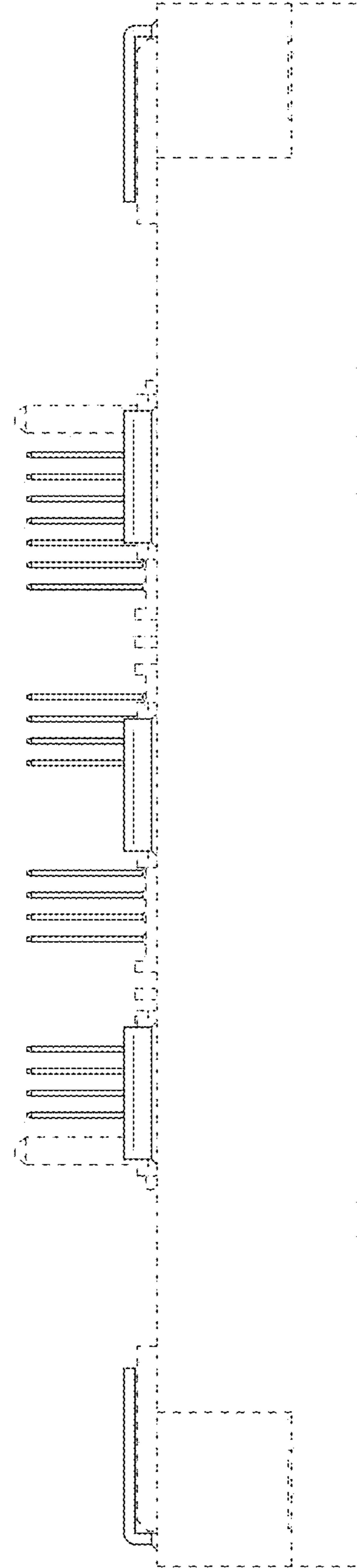


Fig. 7

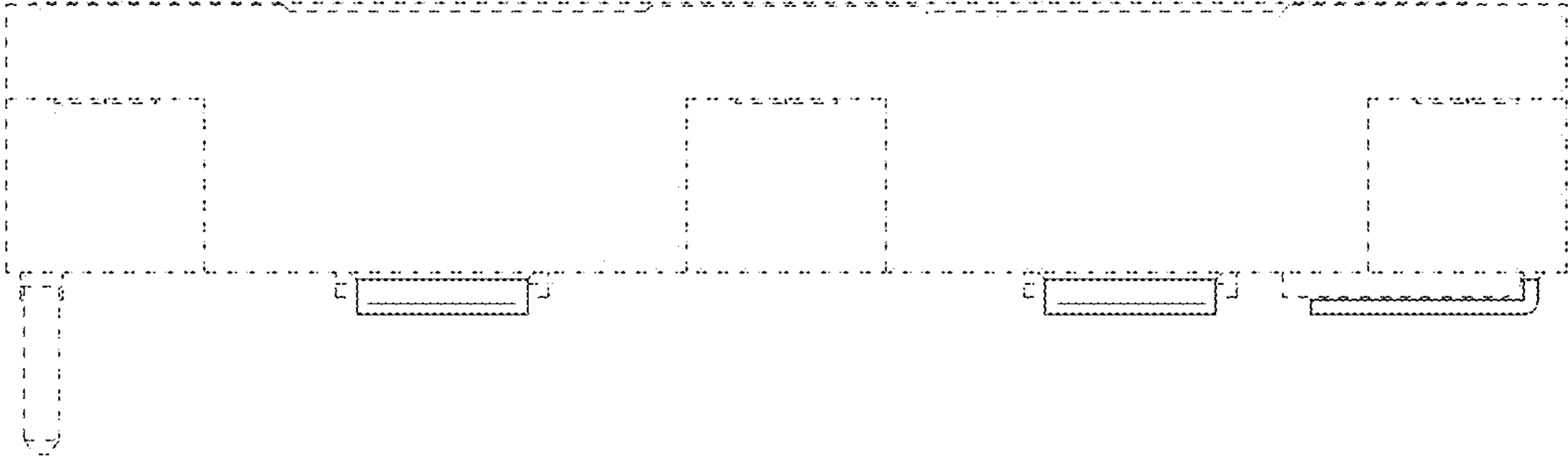


Fig. 6

